

ABSTRACT

METHOD OF TEMPORARILY ATTACHING A RIGID CARRIER TO A SUBSTRATE

Method for temporarily attaching a substrates to a rigid carrier is described which includes forming a sacrificial layer of a thermally-decomposable polymer, e.g., poly(alkylene carbonate), and bonding the flexible substrate to the rigid carrier with the sacrificial layer positioned therebetween. Electronic components and/or circuits may then be fabricated or other semiconductor processing steps employed (e.g., backgrinding) on the attached substrate. Once fabrication is completed, the substrate may be detached from the rigid carrier by heating the assembly to decompose the sacrificial layer.

None of the figures



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